ABSTRACT

The wafer supporting device of the present invention comprises a wafer support, disposed within a process chamber in a semiconductor manufacturing apparatus having respective heat sources in upper and lower portions thereof; a lift member extending from the outside of the support area of the wafer support to the inside and having an inclined upper surface; an arc-shaped lift ring for supporting the lift member; and a lift pin, adapted to vertically move through a through hole in the wafer support, having an upper end part connected to the lift ring; wherein the through hole is covered and substantially closed with the lift ring when the lift pin descends. This eliminates the unevenness in temperature distribution caused by the through hole.